



Material Content Data Sheet



Sales Product Name		TLE9252VLC		Issued		1. August 2018		
MA#		MA001983724						
Package		PG-TSON-14-3		Weight*		42.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.053	2.51	2.51	25055	25055
leadframe	inorganic material	phosphorus	7723-14-0	0.005	0.01		119	
	non noble metal	zinc	7440-66-6	0.020	0.05		477	
	non noble metal	iron	7439-89-6	0.401	0.95		9534	
wire	non noble metal	copper	7440-50-8	16.263	38.71	39.72	387103	397233
	non noble metal	copper	7440-50-8	0.090	0.21	0.21	2149	2149
	encapsulation	organic material	carbon black	1333-86-4	0.046	0.11		1093
encapsulation	plastics	epoxy resin	-	2.366	5.63		56310	
	inorganic material	silicondioxide	60676-86-0	20.556	48.93	54.67	489298	546701
leadfinish	non noble metal	tin	7440-31-5	0.621	1.48	1.48	14787	14787
plating	noble metal	silver	7440-22-4	0.091	0.22	0.22	2159	2159
glue	plastics	epoxy resin	-	0.125	0.30		2979	
	noble metal	silver	7440-22-4	0.375	0.89	1.19	8937	11916
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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